

L Number	Hits	Search Text	DB	Time stamp
-	362	applied adj materials and chamber and exhaust adj gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/09 11:55
-	1243	process adj gas and flow adj rate and residue	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/09 11:55
-	66	(applied adj materials and chamber and exhaust adj gas) and (process adj gas and flow adj rate and residue)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/05 15:32
-	14	("5331134" "5648175" "5663865" "5763010" "5807785" "5812403" "5935334" "6001728" "6079354" "6090167" "6099647" "6114216" "6121163" "6191026").PN.	USPAT	2003/09/05 15:36
-	621	process adj gas and flow adj rate and residue and chamber and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/05 15:37
-	72	restricting and (process adj gas and flow adj rate and residue and chamber and substrate)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/05 15:38
-	21925	shin adj etsu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/09 11:55
-	2	process adj gas and flow adj rate and residue and (shin adj etsu)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/09 11:56
-	20	purge adj gas and (shin adj etsu)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/09 11:56